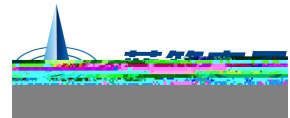


MB1F-05~MB10F-05

Rev.E Jan.-2021



DATA SHEET

/ Revised record

D	2017-5				
E	2021-1-27	4/7	0.5-0.8	e0.5-0.7 5 7	

/ Descriptions

0.5A MBF
0.5A Surface Mount Glass Passivated Bridge Rectifier, MBF thin package。

/ Features

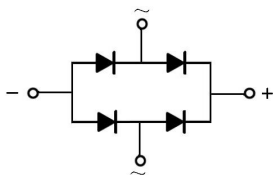
100V~1000V 0.5A

Glass Passivated Chip Junction, Reverse Voltage:100to1000V, Forward Current: 0.5A, High Surge Current Capability, Designed for Surface Mount Application, Halogen free product.

/ Applications

General purpose.

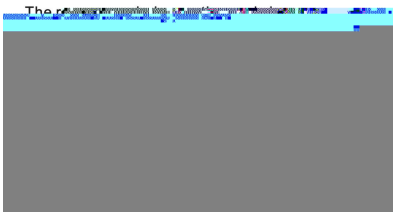
/ Equivalent Circuit



/ Pinning



PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)

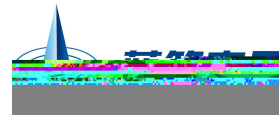


/ Marking

See Marking Instructions.

MB1F-05~MB10F-05

Rev.E Jan.-2021



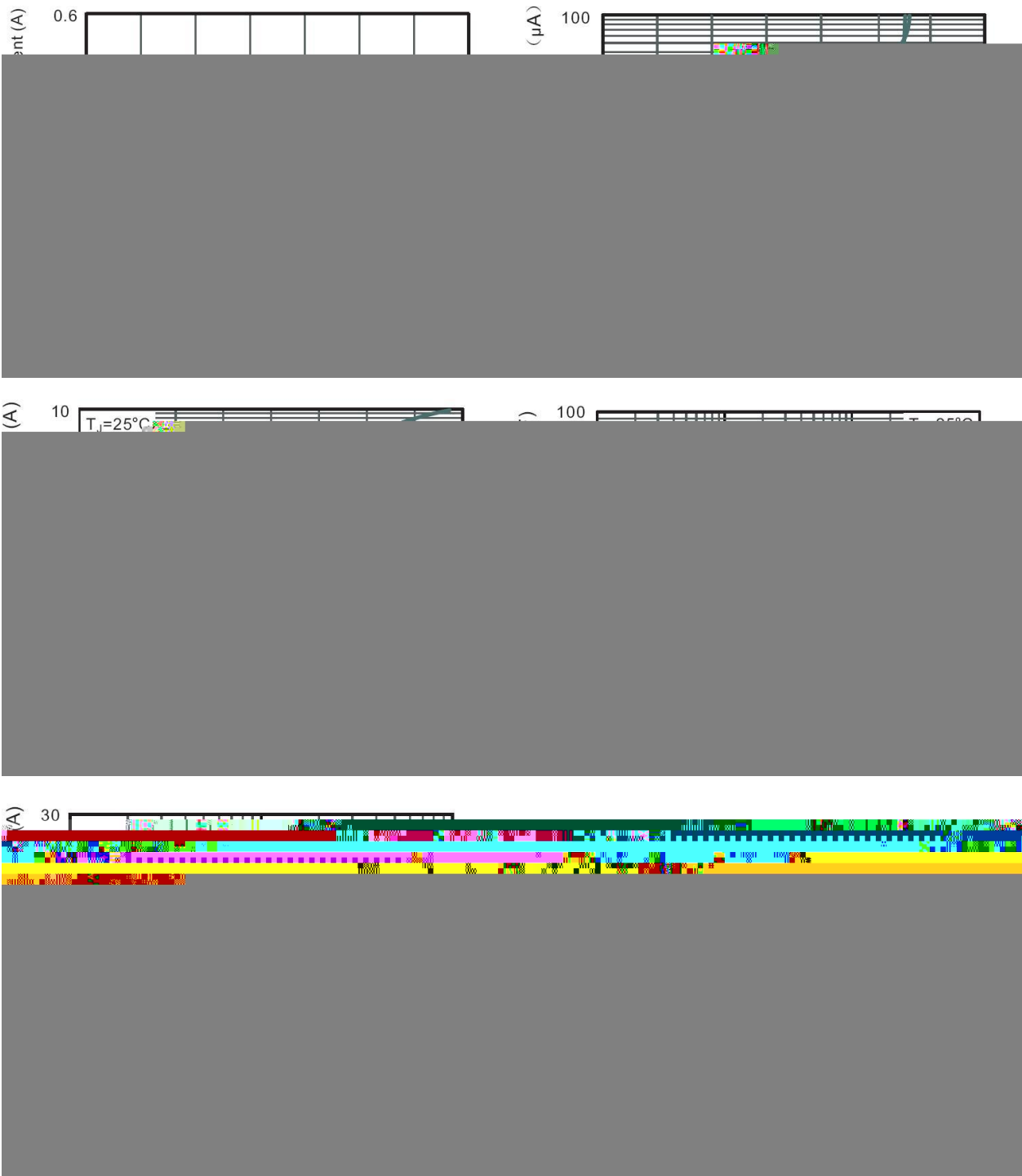
DATA SHEET

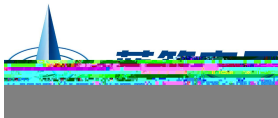
参数 Parameter	符号 Symbol	数值 Rating						单位 Unit
		MB1F-05	MB2F-05	MB4F-05	MB6F-05	MB8F-05	MB10F-05	
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	100	200	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at Ta = 50℃	I _{F(AV)}	0.5						A
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	20						A
Typical Junction Capacitance ¹⁾	C _j	13						pF
Typical Thermal Resistance ²⁾	R _{θJA}	120						℃/W
	R _{θJL}	35						

Operating and Storage Temperature Range: -40~+125 $^{\circ}\text{C}$

a yO

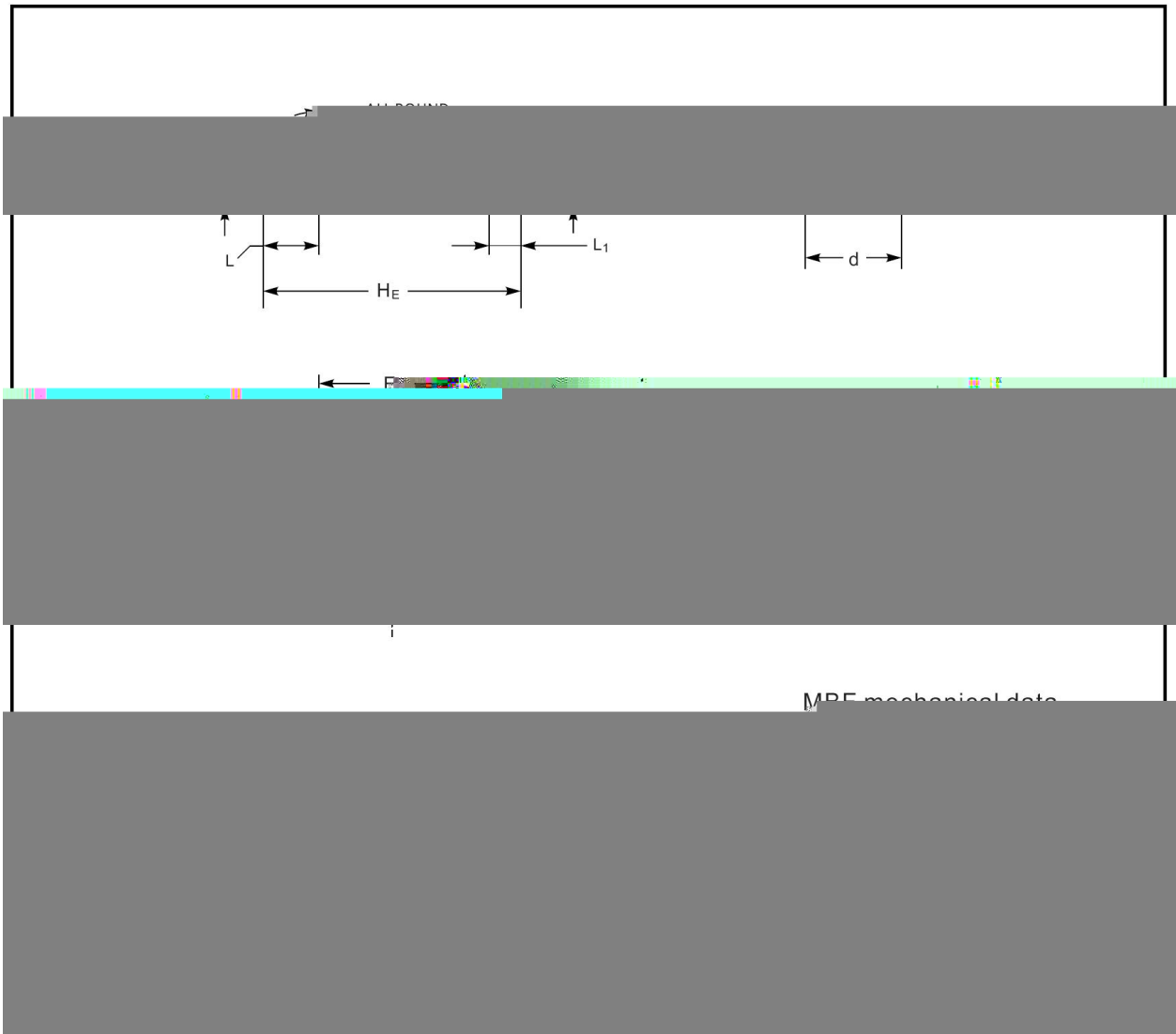
/ Electrical Characteristic Curve





/ Package Dimensions

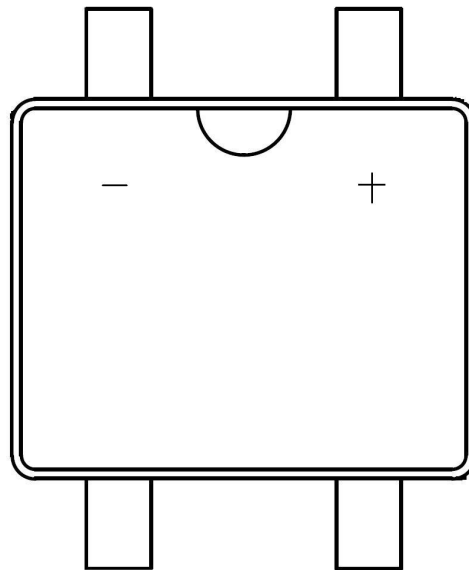
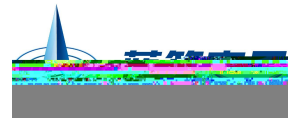
MBF

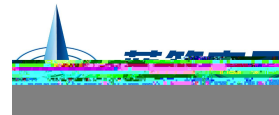


/ Marking Instructions

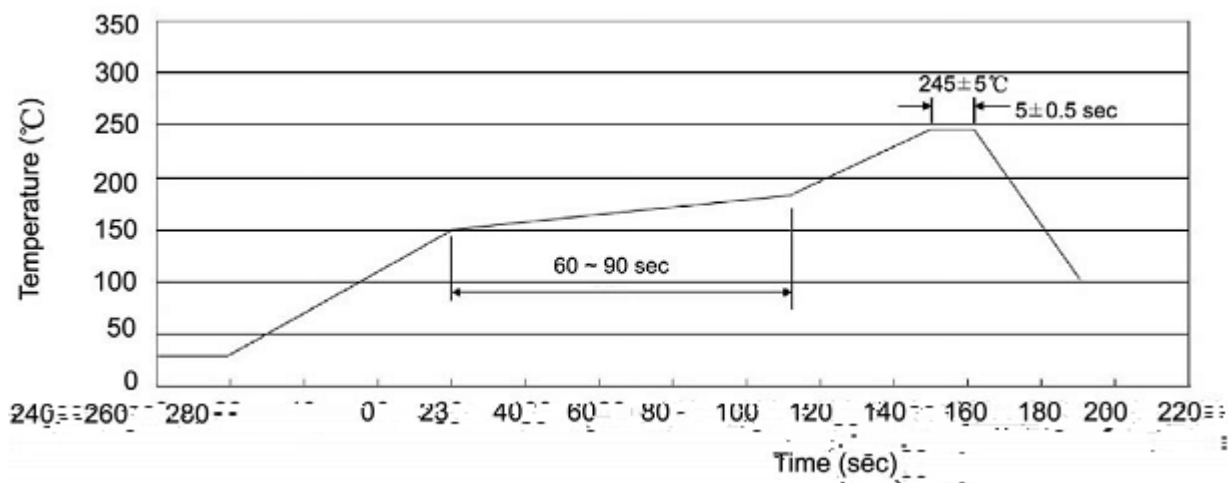
Marking

Type number	Marking code





() / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

/ Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

/ Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
MBF	5000	2	10000	7	70000	13" ×12	336X336X40	380X335X366

/ Notices